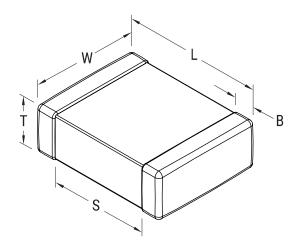


C1206X139DATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 1.3 pF, +/-0.5 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

 Dimensions

 Chip Size
 1206

 L
 3.3mm +/-0.4mm

 W
 1.6mm +/-0.35mm

 T
 0.78mm +/-0.20mm

 S
 1.5mm MIN

 B
 0.6mm +/-0.25mm

Click here for the 3D model.

Packaging Specifications Packaging T&F

Packaging Quantity

T&R, 330mm, Plastic Tape 10000

Specifications	
Capacitance	1.3 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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